

# PCM-5895

## Compact Board

# Thermal Image Analysis Report

Report NO: 07E080002  
Release Date: Feb 1, 2007

2007/02/1

Issue Stamp

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Manager

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# Thermal Image Analysis

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**I . Model Name: PCM-5895 Rev. A0.2**

**II . Description: Compact Board**

**III . Date: Feb 1, 2007**

**IV. Measure Site: AAEON QE Dept.**

**V. Issued by : Andrew Ku**

**VI. Equipment:**

**TVS-100 series by NIPPON AVIONICS CO., LTD.**

**VII. Simulation Environment:**

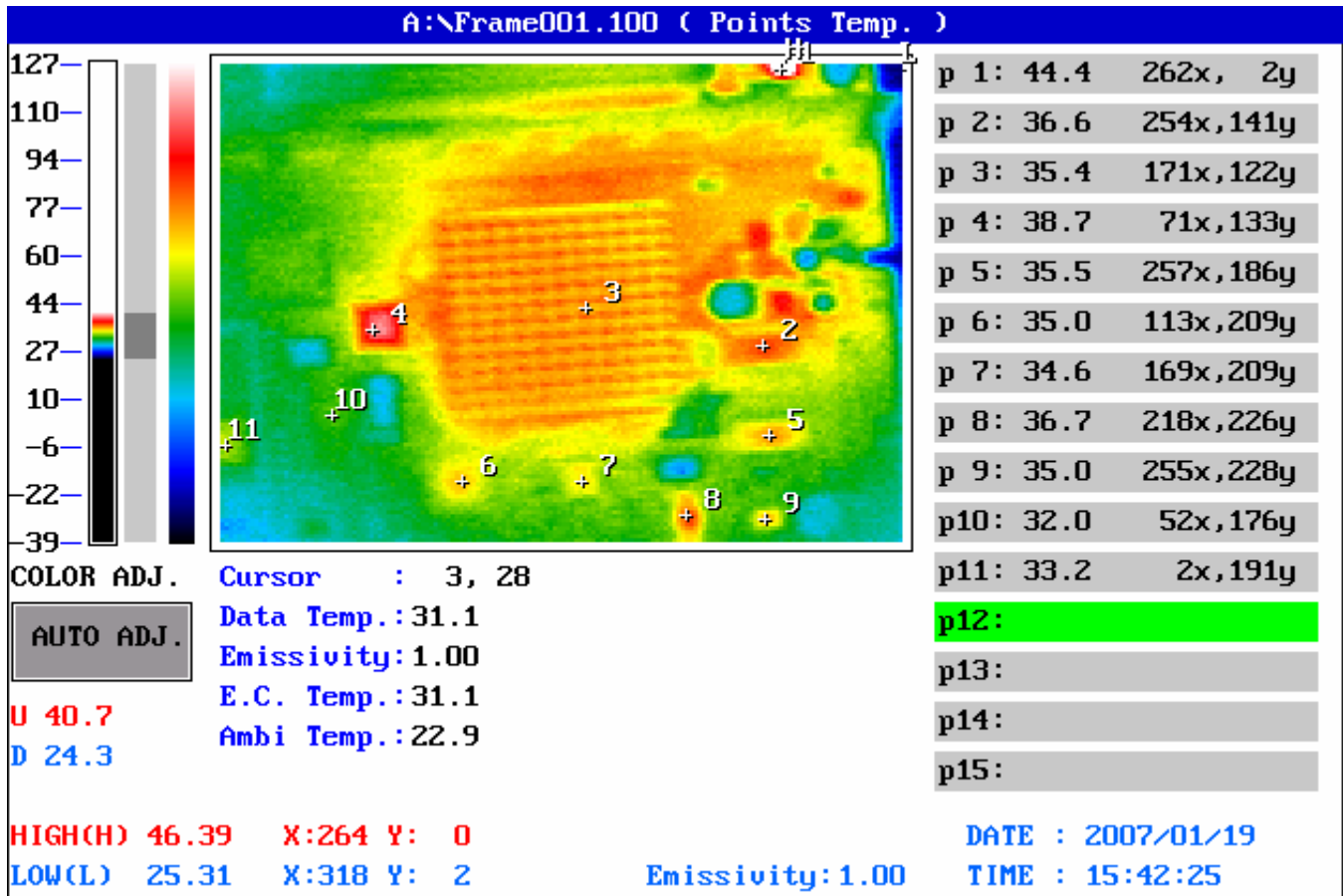
- **Temperature: Component Side-1 : 22.9°C , Component Side-2 : 22.8°C , Component Side-3 : 22.7°C**

• **System Configuration :**

- **PCB Version : PCM-5895 Rev.A 0.2**
- **CPU : Geode –LX 500MHz**
- **RAM : Transcend / 0636SR V58C2512804SBI /DDR400 /1GB**
- **BIOS : PCM-5895 BIOS Rev 0.3(01/02/2007)**
- **CF Card : N/A**
- **HDD : Maxtor 6Y080L0 YAR41BW0 80GB**
- **Application Software: Run Prime95 under Windows XP Professional V2002 Service Pack 2**
- **Take Picture Time: After Power on 2 hours.**

### Temperature Profile Test:

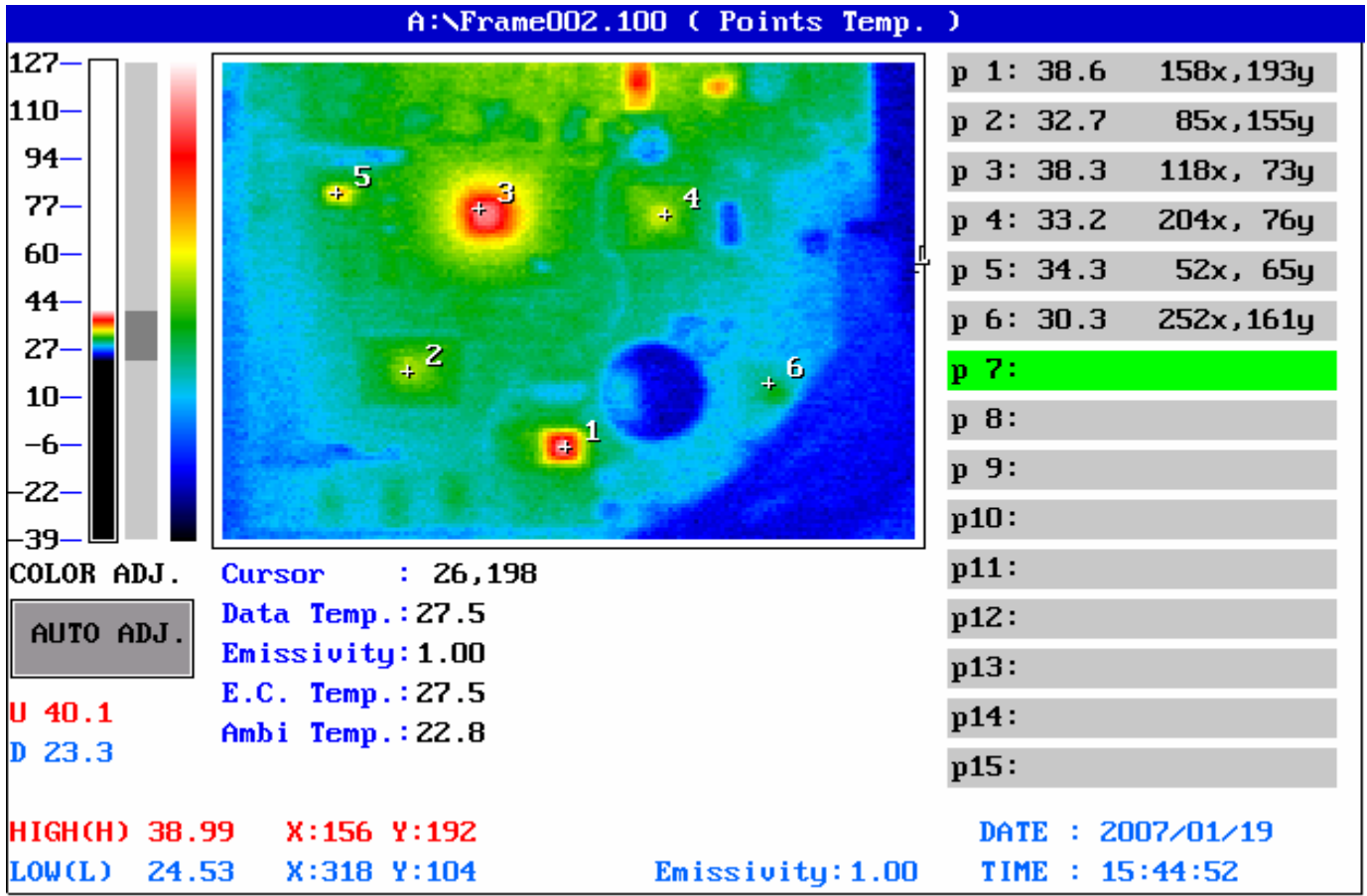
#### Component Side-1:



Point	Position	Describe	Tc (°C)	Tm (22.9°C)	Tm (60°C)	Note
1	U1	(TF)IC.SMD SO8.3A Linear Regulator.Anpec.APL5331KC-TRL	115	44.4	81.5	
2	U62	(TF)IC.SMD.TSSOP56.FlatLink Transmitter.TI.SN75LVDS83	115	36.6	73.7	
3	U6	(TF)AMD CPU.BGU481.LX-800.500MHz.1.25V.AMD.ALXD800EEXJ2VD	110	35.4	72.5	
4	U7	(TF)IC.SMD CPLD VQFP 44P.CS:33726.Xilinx.XC9536-15VQG44C	115	38.7	75.8	
5	U56	(TF)IC.SMD.TSSOP56.FlatLink Transmitter.TI.SN75LVDS83	115	35.5	72.6	
6	U53	(TF)IC.SMD TFBGA.160P.PCI to ISA Bridge Chip.ITE.IT8888G-L	125	35.0	72.1	
7	U16	(TF)IC.SMDCPLDQFP48P.CS:D03A.PCI-675F.PCIARBITOR.Lattice.LC4032V-7 5TN48C	115	34.6	71.7	
8	U19	(TF)IC.SMD.SSOP28.Clock Generator.ICS.MK1491-09FLN	125	36.7	73.8	
9	U20	(TF)IC.SMD SOP 8P.Clock Output Buffer.ICS.ICS9112M-16LF-T	100	35.0	72.1	
10	U10	(TF)IC.SMD SO28.Stand-alone CAN Controller.PHILIPS.SJA1000T/N1	125	32.0	69.1	
11	U12	(TF)GAL.Lattice.16V8D.CS:35CBh.MB-668/MB-662.DOC Decoder		33.2	70.3	

1. Tm (Measured operation temperature) must be less than Tc (Specified case temperature) +5 degree C  
 2. Any Tm value showed in red words which meaning the value is over the Tc+ 5 degree C of this device specification

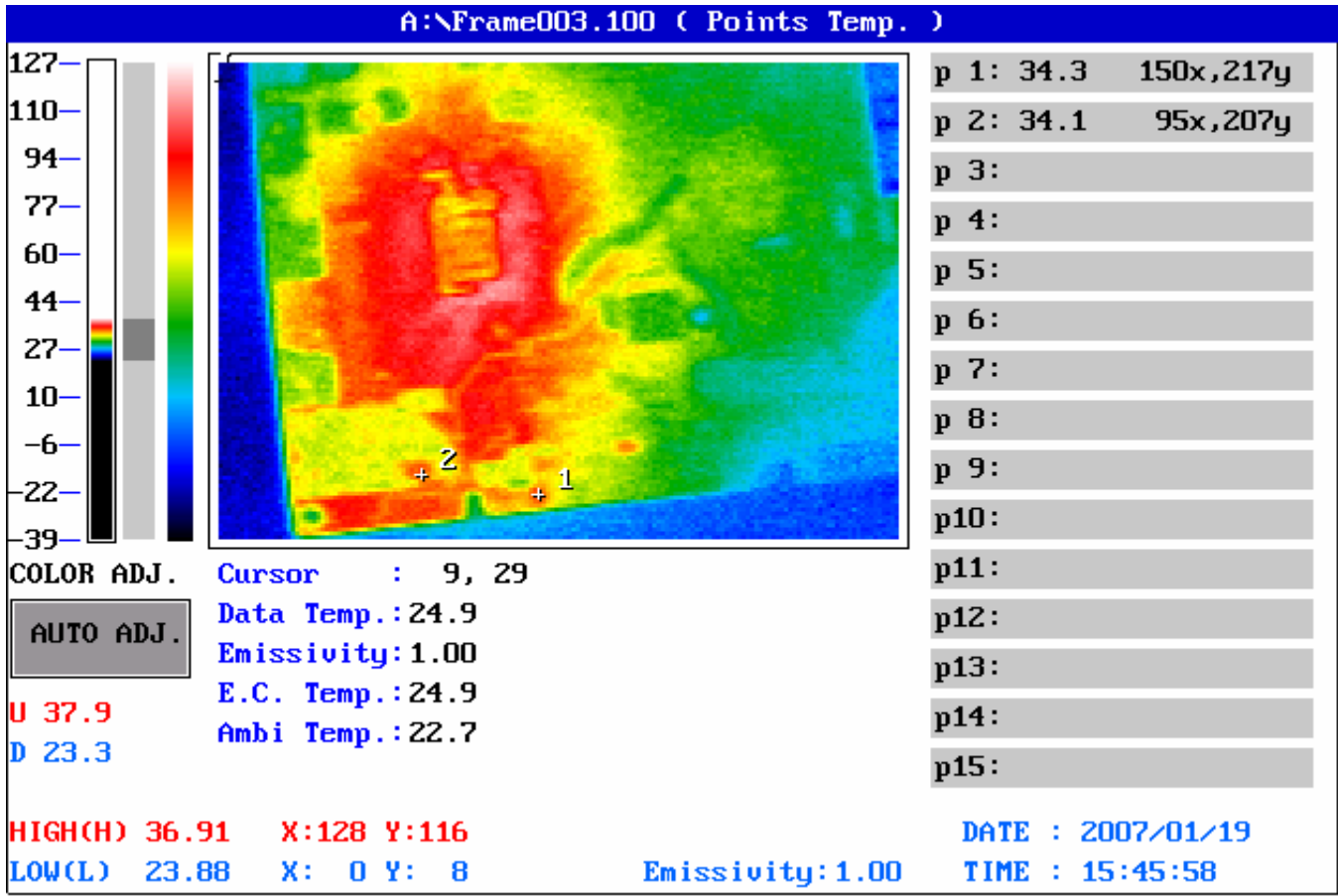
Component Side-2:



Point	Position	Describe	Tc (°C)	Tm (22.8°C)	Tm (60°C)	Note
1	U42	(TF)IC.SMD.2 Channel Audio Codec.Realtek.ALC203-LF	100	38.6	75.8	
2	U40	(TF)IC.SMD.QFP128P Super I/O.ITE.IT8712F/KX-L	100	32.7	69.9	
3	U32	(TF)IC.SMD208PBGA.I/OCompanion.Multi-FunctionSouth Bridge.AMD.CS5536AD	110	38.3	75.5	
4	U59	(TF)IC.SMD.LQFP 100P PCI Ethernet Chip.RELTEK.RTL8139DL	125	33.2	70.4	
5	U29	(TF)IC.SMDSO-8.1.5A.LowDropout Regulator.Adj(1.2~4.8V).SEMTECH.SC1565IS-TRT	110	34.3	71.5	
6	U41	(TF)IC.SMD.LQFP 100P PCI Ethernet Chip.RELTEK.RTL8139DL	125	30.3	67.5	

3. Tm (Measured operation temperature) must be less than Tc (Specified case temperature) +5 degree C  
 4. Any Tm value showed in red words which meaning the value is over the Tc+ 5 degree C of this device specification

Component Side-3:



Point	Position	Describe	Tc (°C)	Tm (22.7°C)	Tm (60°C)	Note
1	U8	(TF)IC.SMD TSSOP14.Synchronous Buck Regulator.NS.LM2727	150	34.3	71.6	
2	C476	(TF)SPCAP.150uF.6.3V.20%.D(7.3*4.3*2.8mm).18mOhm SMD.Panasonic.ECGUD0J151ER	105	34.1	71.4	

5. Tm (Measured operation temperature) must be less than Tc (Specified case temperature) +5 degree C  
 6. Any Tm value showed in red words which meaning the value is over the Tc+ 5 degree C of this device specification